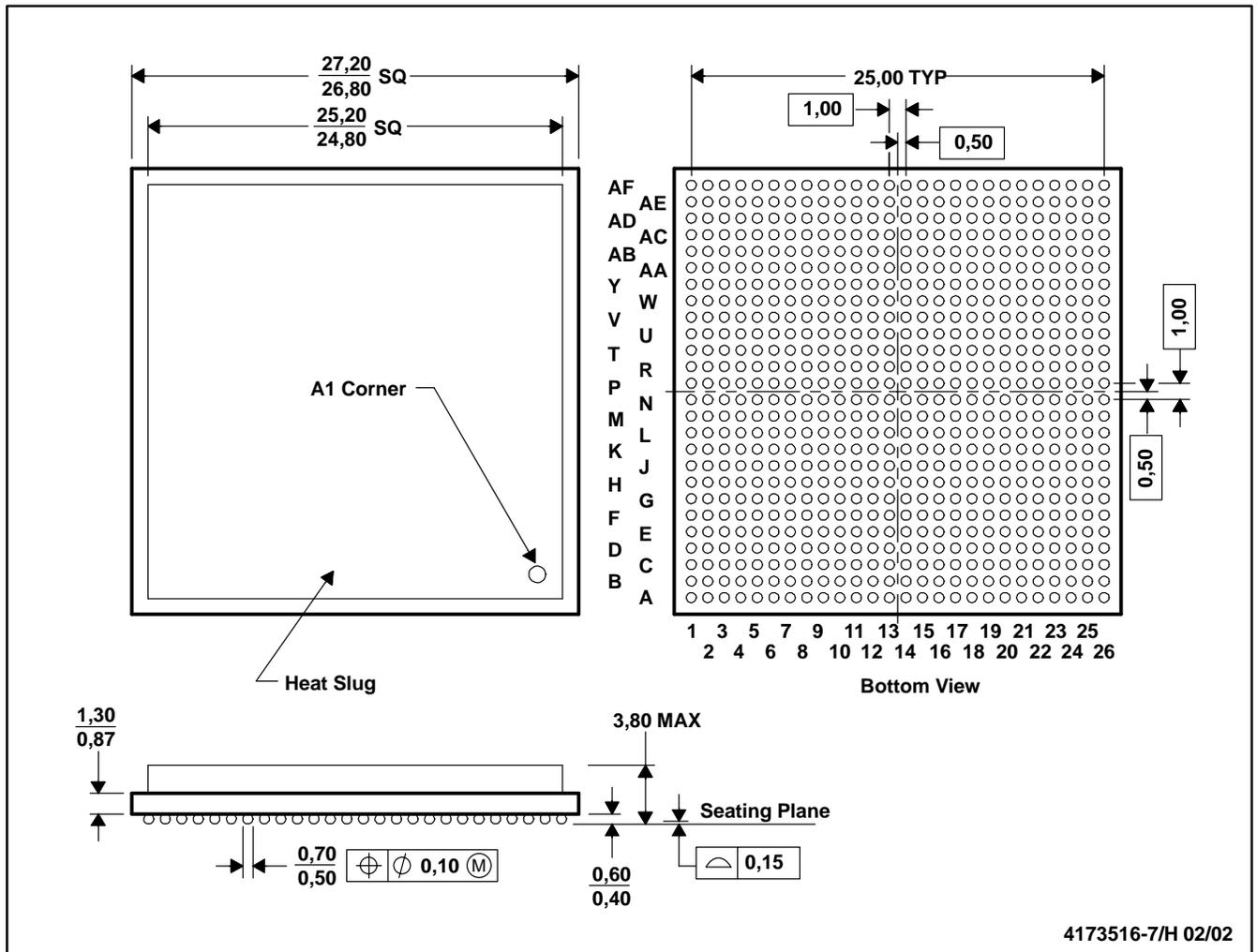


GJL (S-PBGA-N676)

PLASTIC BALL GRID ARRAY



4173516-7/H 02/02

- NOTES:
- A. All linear dimensions are in millimeters
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced plastic package with heat slug (HSL).
 - D. Falls with JEDEC MO-151/AAL-1
 - E. Flip chip application only

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